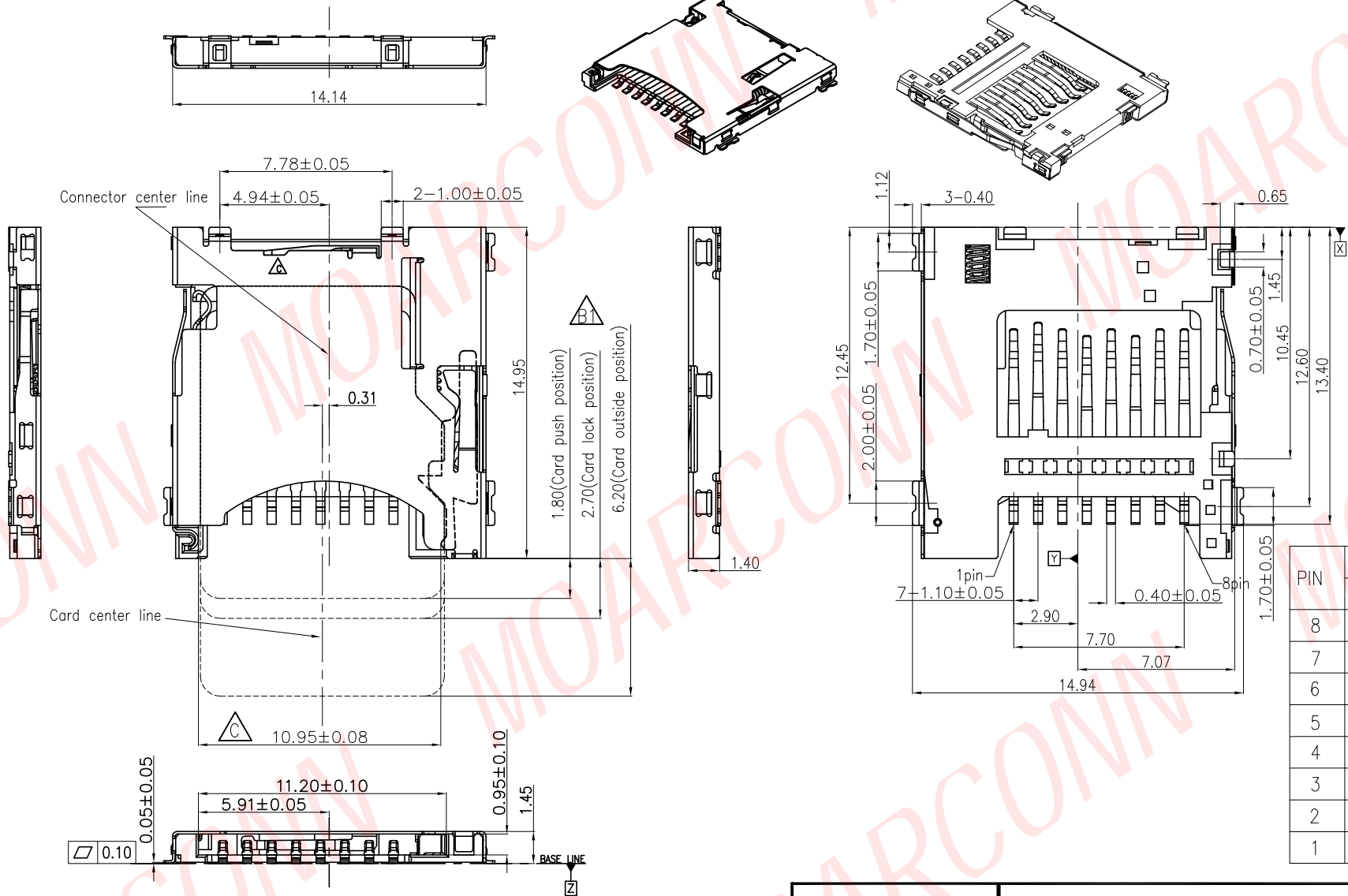


All materials, plating and process meet HF requirements.

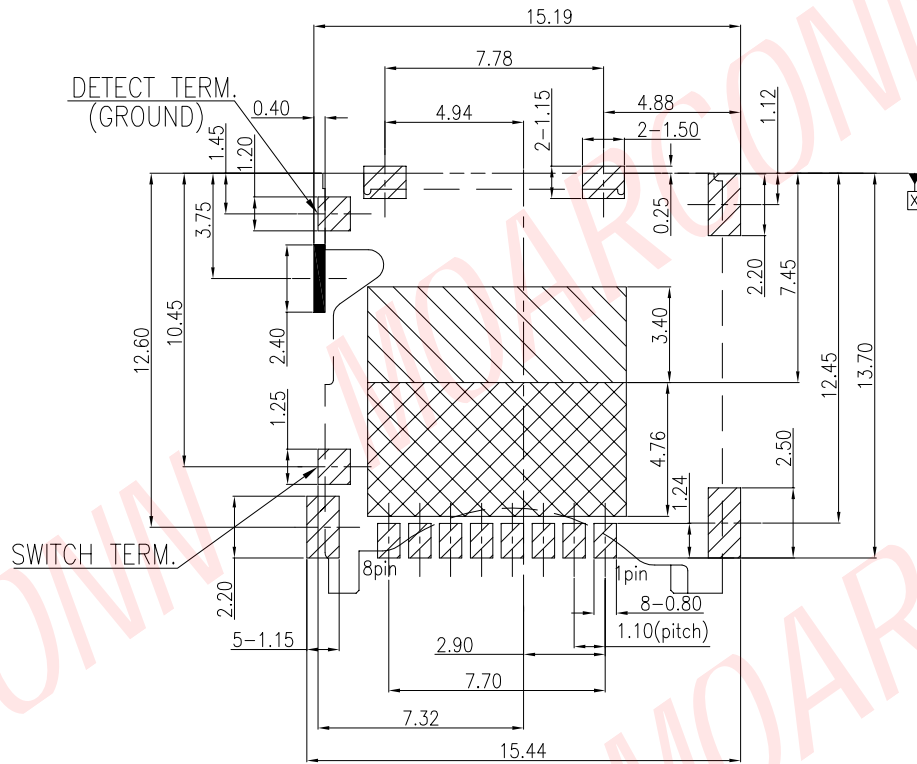


PIN	T/F CARD
	microSD
8	P8 Dat1
7	P7 Dat0
6	P6 VSS
5	P5 CLK
4	P4 VDD
3	P3 CMD
2	P2 CD/Dat3
1	P1 Dat2





REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
C	ER229087	Modify the drawing to match the product Δ	Aaron	2022.09.16
B1	ECN20180707001	Modify the dimension	janyz	2018.07.02
B	----	Drawing optimization	ping	2016.11.30

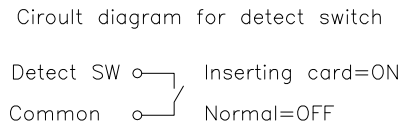
		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
		DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	PRODUCT NAME : Micro-SD CARD CONN. H1.45mm	DRAWING: Aaron	DATE: 2022.09.16
DIMENSION TOLERANCE X.X: ± 0.30 X.XX: ± 0.20 X.XXX: ± 0.05 ANGULAR: ± 2'	PRODUCT NO. : TF145-T1251-01	CHECK: DATE:	DRAWING NO. : D-TF145-T1251-01	APPROVED: DATE:	
		SCALE: 1:1	DWG ID: C D	REV.: C	PAGE: 1 OF 2

All materials, plating and process meet HF requirements.




RECOMMEND P.C.B LAYOUT
(General tolerance ± 0.05)



-  PAD AREA
-  PATTERN PROHIBITION AREA
-  SOLDER PROHIBITION AREA
-  PROHIBITED AREA



Specification

1. MATERIAL:
 - 1.1 Insulator: High Temperature Thermoplastic, (LCP, MG350), UL Black 94V-0.
 - 1.2 Contact: Phosphor Bronze (C5210R-H, T=0.15 \pm 0.03mm)
 - 1.3 Shell: SUS304-H T=0.12 \pm 0.03mm
2. Plating:
 - 2.1 Contact: Plated 50u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 100u"min Sn over Ni on solder area
 - 2.2 Shell: Plated 50u"min Ni Overall
Plated 1u"min Au Selective Contact Area
3. Property:
 - 3.1 Current Rating : 0.5A AC/DC max.
 - 3.2 Voltage Rating : 3.3V/5V(AC/DC)
 - 3.3 Contact Resistance: Contact Pin 100m Ω max.
 - 3.4 Insert/Pulling Force: 40N Max / 0.5~40N
 - 3.5 Smt Solder Temperature: Should Under 260°C
 - 3.6 Operation Temperature Range: -40~+85°C

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
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MOARCONN MORE CONNECTIONS SMART FUTURE		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
DIMENSIONS INIT: mm		PRODUCT NAME : Micro-SD CARD CONN. H1.45mm	DRAWING: Aaron	DATE: 2022.09.16	
UNLESS OTHERWISE SPECIFIABLE		PRODUCT NO. : TF145-T1251-01	CHECK:	DATE:	
DIMENSION TOLERANCE		DRAWING NO. : D-TF145-T1251-01	APPROVED:	DATE:	
X.X: \pm 0.30	X.XX: \pm 0.20	 		SCALE:	DWG ID:
X.XXX: \pm 0.05	ANGULAR: \pm 2'			1:1	C D